

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jaw-Jung Shin</td> <td>06/25/2012</td> </tr> <tr> <td>Shy-Jay Lin</td> <td>06/25/2012</td> </tr> <tr> <td>Hua-Tai Lin</td> <td>06/25/2012</td> </tr> <tr> <td>Burn Jeng Lin</td> <td>06/28/2012</td> </tr> </tbody> </table>		Name	Execution Date	Jaw-Jung Shin	06/25/2012	Shy-Jay Lin	06/25/2012	Hua-Tai Lin	06/25/2012	Burn Jeng Lin	06/28/2012		
Name	Execution Date												
Jaw-Jung Shin	06/25/2012												
Shy-Jay Lin	06/25/2012												
Hua-Tai Lin	06/25/2012												
Burn Jeng Lin	06/28/2012												
RECEIVING PARTY DATA													
<table border="1"> <tr> <td>Name:</td> <td>Taiwan Semiconductor Manufacturing Company, Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Rd. 6</td> </tr> <tr> <td>Internal Address:</td> <td>Science-Based Industrial Park</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	Street Address:	No. 8, Li-Hsin Rd. 6	Internal Address:	Science-Based Industrial Park	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.												
Street Address:	No. 8, Li-Hsin Rd. 6												
Internal Address:	Science-Based Industrial Park												
City:	Hsin-Chu												
State/Country:	TAIWAN												
Postal Code:	300-77												
PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13534765</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13534765								
Property Type	Number												
Application Number:	13534765												
CORRESPONDENCE DATA													
Fax Number:	2142000853												
Phone:	214-651-5000												
Email:	ipdocketing@haynesboone.com												
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>													
Correspondent Name:	Haynes and Boone LLP												
Address Line 1:	2323 Victory Avenue												
Address Line 2:	Suite 700												
Address Line 4:	Dallas, TEXAS 75219												
ATTORNEY DOCKET NUMBER:	24061.2149/2012-0193												
NAME OF SUBMITTER:	David M. O'Dell												
Total Attachments: 3 source=2149Assignment#page1.tif source=2149Assignment#page2.tif source=2149Assignment#page3.tif													

OP \$40.00 13534765

PATENT

Docket No.: 2012-0193 / 24061.2149

Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|---------------|----|---|
| (1) | Jaw-Jung Shin | of | 10F, No. 72-11, Lane 531, Sec. 1, Guangfu Road, East District
Hsinchu City 300, Taiwan, R.O.C. |
| (2) | Shy-Jay Lin | of | No. 15, Alley 36, Lane 134, Yuanshan Road
Jhudong Township, Hsinchu County 310, Taiwan, R.O.C. |
| (3) | Hua-Tai Lin | of | No. 26, Alley 10, Lane 194, Gaofeng Road
Hsinchu City 300, R.O.C. |
| (4) | Burn Jeng Lin | of | 153 Guang Fu Road, Sec. 1, Lane 89, 1st FL
Hsin-Chu City, Taiwan, R.O.C. |

have invented certain improvements in

METHOD FOR PROXIMITY CORRECTION

for which we have filed and executed an application for Letters Patent of the United States of America on June 27, 2012, as U.S. Serial No. 13/534,765; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue

Docket No.: 2012-0193 / 24061.2149

Customer No.: 42717

applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Jaw-Jung Shin

Residence Address: 10F, No. 72-11, Lane 531, Sec. 1, Guangfu Road, East District
Hsinchu City 300, Taiwan, R.O.C.

Dated: 6/25/2012

Shin, Jaw-Jung
Inventor Signature

Inventor Name: Shy-Jay Lin

Residence Address: No. 15, Alley 36, Lane 134, Yuanshan Road
Jhudong Township, Hsinchu County 310, Taiwan, R.O.C.

Dated: June 25 2012

Shy-Jay Lin
Inventor Signature

Inventor Name: Hua-Tai Lin

Residence Address: No. 26, Alley 10, Lane 194, Gaofeng Road
Hsinchu City 300 R.O.C.

Dated: 6/25/2012

Hua-Tai Lin
Inventor Signature

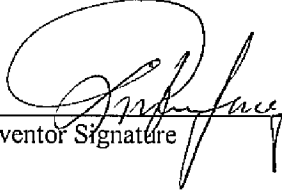
Docket No.: 2012-0193 / 24061.2149

Customer No.: 42717

Inventor Name: Burn Jeng Lin

Residence Address: 153 Guang Fu Road, Sec. 1, Lane 89, 1st FL
Hsin-Chu City, Taiwan, R.O.C.

Dated: Jun 28, 2012


Inventor Signature